

Serial-in / Parallel-out Driver Series

# 4-input Serial-in / Parallel-out Drivers

## BU2092F BU2092FV

### Description

BU2092F/BU2092FV are an open drain output driver. It incorporates a built-in shift register and a latch circuit to turn on a maximum of 12 output by a 4-line interface, linked to a microcontroller.  
An open drain output provides maximum 25mA current.

### Features

- LED can be driven directly
- 12bit parallel output
- This product can be operated on low voltage

### Key Specifications

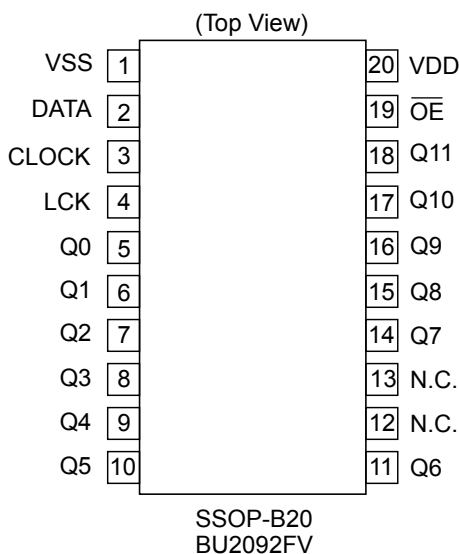
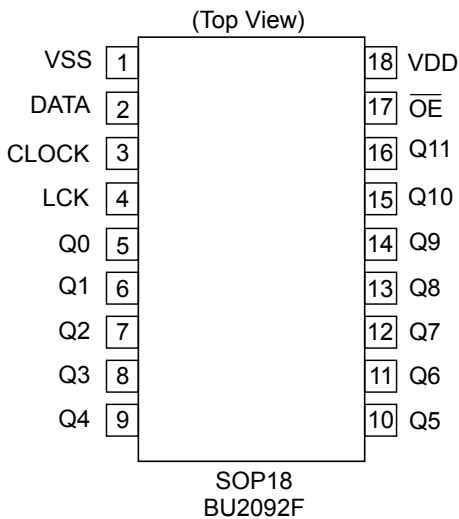
- Power supply voltage range: 2.7V to 5.5V
- Output voltage: 0V to +25.0V
- Operating temperature range: -25°C to +75°C

### Package

SOP18  
SSOP-B20

W(Typ) x D(Typ) x H(Max)  
11.20mm x 7.80mm x 2.01mm  
6.50mm x 6.40mm x 1.45mm

### Pin Configurations

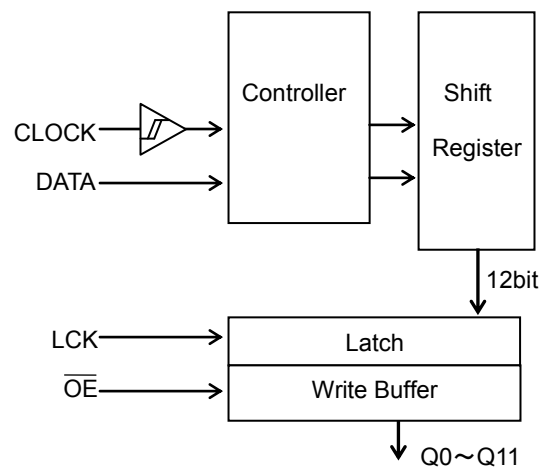


SOP18  
BU2092F



SSOP-B20  
BU2092FV

### Block Diagrams



## Pin Descriptions

## BU2092F

Pin No.	Pin Name	I/O	Function						
1	VSS	-	Ground						
2	DATA	I	Serial Data Input						
3	CLOCK	I	Shift clock of DATA (Rising Edge Trigger)						
4	LCK	I	Latch clock of DATA (Rising Edge Trigger)						
5	Q0	O	Parallel Data Output (Nch Open Drain ) <table border="1" style="margin-left: 20px;"> <tr> <td>Latch Data</td> <td>L</td> <td>H</td> </tr> <tr> <td>Output</td> <td>ON</td> <td>OFF</td> </tr> </table>	Latch Data	L	H	Output	ON	OFF
Latch Data	L			H					
Output	ON			OFF					
6	Q1								
7	Q2								
8	Q3								
9	Q4								
10	Q5								
11	Q6								
12	Q7								
13	Q8								
14	Q9								
15	Q10								
16	Q11								
17	$\overline{OE}$	I	Output Enable ("H" level : Output is OFF)						
18	VDD	-	Power Supply						

## BU2092FV

Pin No.	Pin Name	I/O	Function						
1	VSS	-	Ground						
2	DATA	I	Serial Data Input						
3	CLOCK	I	Shift clock of DATA (Rising Edge Trigger)						
4	LCK	I	Latch clock of DATA (Rising Edge Trigger)						
5	Q0	O	Parallel Data Output (Nch Open Drain ) <table border="1" style="margin-left: 20px;"> <tr> <td>Latch Data</td> <td>L</td> <td>H</td> </tr> <tr> <td>Output</td> <td>ON</td> <td>OFF</td> </tr> </table>	Latch Data	L	H	Output	ON	OFF
Latch Data	L			H					
Output	ON			OFF					
6	Q1								
7	Q2								
8	Q3								
9	Q4								
10	Q5								
11	Q6								
12	N.C.			-	Non Connected				
13	N.C.			-	Non Connected				
14	Q7	O	Parallel Data Output (Nch Open Drain ) <table border="1" style="margin-left: 20px;"> <tr> <td>Latch Data</td> <td>L</td> <td>H</td> </tr> <tr> <td>Output</td> <td>ON</td> <td>OFF</td> </tr> </table>	Latch Data	L	H	Output	ON	OFF
Latch Data	L			H					
Output	ON			OFF					
15	Q8								
16	Q9								
17	Q10								
18	Q11								
19	$\overline{OE}$	I	Output Enable ("H" level : Output is OFF)						
20	VDD	-	Power Supply						

**Absolute Maximum Ratings**

Parameter	Symbol	Limits	Unit	
Supply Voltage	V <sub>DD</sub>	-0.3 to +7.0	V	
Input Voltage	V <sub>IN</sub>	V <sub>SS</sub> -0.3 to V <sub>DD</sub> +0.3	V	
Output Voltage	V <sub>O</sub>	V <sub>SS</sub> to +25.0	V	
Operating Temperature	T <sub>opr</sub>	-25 to +75	°C	
Storage Temperature	T <sub>stg</sub>	-55 to +125	°C	
Power Dissipation	P <sub>D</sub>	SOP18	0.55 (Note 1)	W
		SSOP-B20	0.65 (Note 2)	

(Note 1) Mounted on 70mm x 70mm x 1.6mm glass epoxy board. Reduce 5.5mW per 1°C above 25°C.

(Note 2) Mounted on 70mm x 70mm x 1.6mm glass epoxy board. Reduce 6.5mW per 1°C above 25°C.

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

**Recommended Operating Conditions (T<sub>A</sub> =25°C, V<sub>SS</sub>=0V)**

Parameter	Symbol	Limits	Unit
Supply Voltage	V <sub>DD</sub>	+2.7 to +5.5	V
Output Voltage	V <sub>O</sub>	0 to 25.0	V

**Electrical Characteristics**

DC Characteristics

(Unless otherwise specified, V<sub>DD</sub>=5V, V<sub>SS</sub>=0V, T<sub>A</sub> =25°C)

Parameter	Symbol	Limits			Unit	Condition
		Min	Typ	Max		
Input high-level Voltage	V <sub>IH</sub>	3.5	-	-	V	-
Input low-level Voltage	V <sub>IL</sub>	-	-	1.5	V	-
Output low-level Voltage	V <sub>OL</sub>	-	-	2.0	V	I <sub>OL</sub> =20mA
Output high-level Leak Current	I <sub>IH</sub>	-	-	10.0	µA	V <sub>O</sub> =25.0V
Output low-level Leak Current	I <sub>IL</sub>	-	-	-5.0	µA	V <sub>O</sub> =0V
Quiescent Current	I <sub>DD</sub>	-	-	5.0	µA	V <sub>IN</sub> =V <sub>SS</sub> or V <sub>DD</sub> Q0 to Q11:OPEN

Electrical Characteristics - continued

Timing Characteristics

(Unless otherwise specified,  $V_{DD}=5V$ ,  $V_{SS}=0V$ ,  $T_A=25^{\circ}C$ )

Parameter	Symbol	Limit			Unit	V <sub>DD</sub> (V)	Condition
		Min	Typ	Max			
Minimum Clock Pulse Width	$t_w$	1000	-	-	ns	3	-
		500	-	-	ns	5	
Minimum Latch Pulse Width (LCK)	$t_w$ (LCK)	1000	-	-	ns	3	-
		500	-	-	ns	5	
Setup Time (LCK→CLOCK)	$t_s$	400	-	-	ns	3	-
		200	-	-	ns	5	
Setup Time (DATA→CLOCK)	$t_{su}$	400	-	-	ns	3	-
		200	-	-	ns	5	
Hold Time (CLOCK→DATA)	$t_H$	400	-	-	ns	3	-
		200	-	-	ns	5	
Propagation (LCK→OUTPUT Q <sub>x</sub> )	$t_{PLZ}$ (LCK)	-	90	-	ns	3	R <sub>L</sub> =5kΩ C <sub>L</sub> =10pF
		-	55	-	ns	5	
	$t_{PZL}$ (LCK)	-	115	-	ns	3	
		-	50	-	ns	5	
Propagation (OE→OUTPUT Q <sub>x</sub> )	$t_{PLZ}$	-	70	-	ns	3	R <sub>L</sub> =5kΩ C <sub>L</sub> =10pF
		-	45	-	ns	5	
	$t_{PZL}$	-	80	-	ns	3	
		-	35	-	ns	5	

Waveform of Timing Characteristics

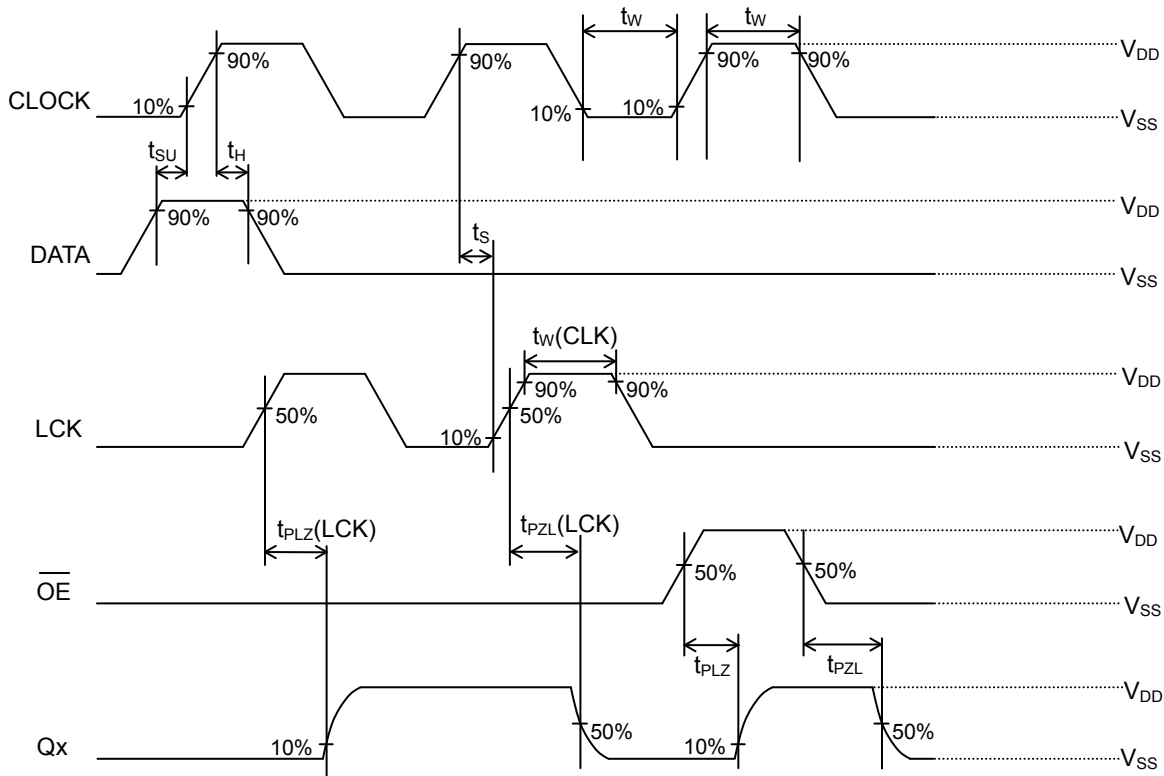


Figure 1. Waveform of Timing Characteristics

Test Circuits (Figures are in case of BU2092F)

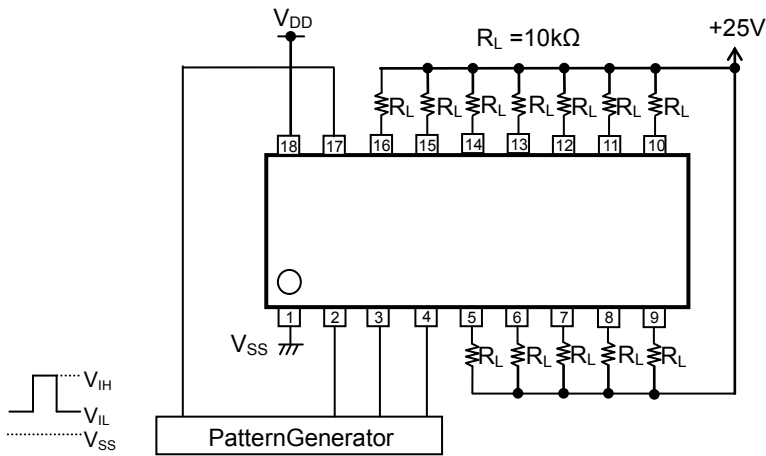


Figure 2. Test Circuit of Input H/L Voltage

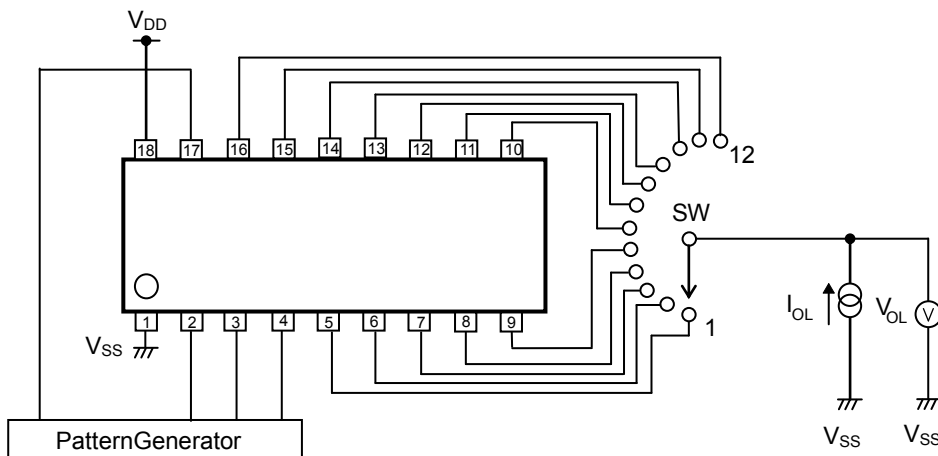


Figure 3. Test Circuit of Output L Voltage

Test Circuits - continued (Figures are in case of BU2092F)

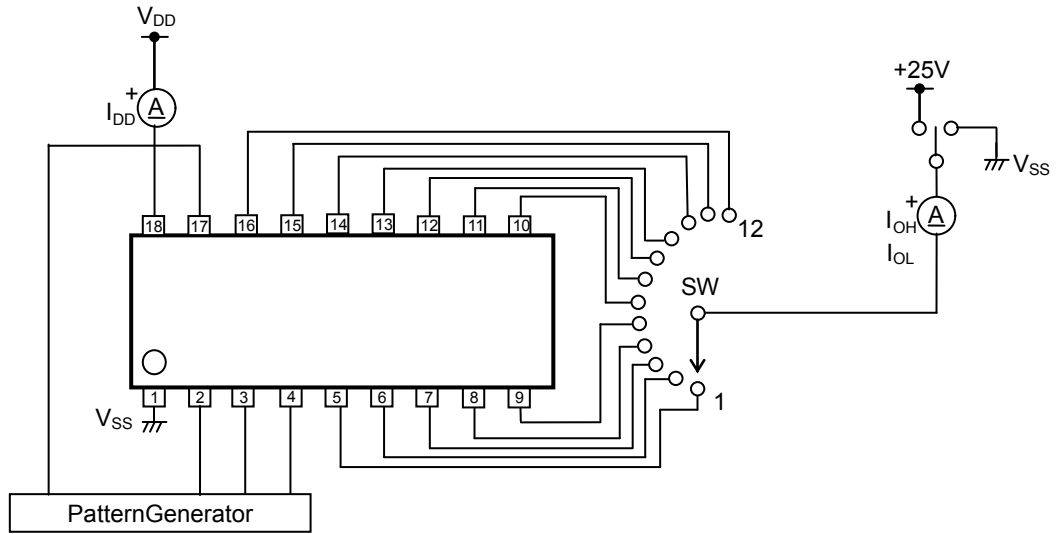


Figure 4. Test Circuit of Output H/L Leak / Static Dissipation Current

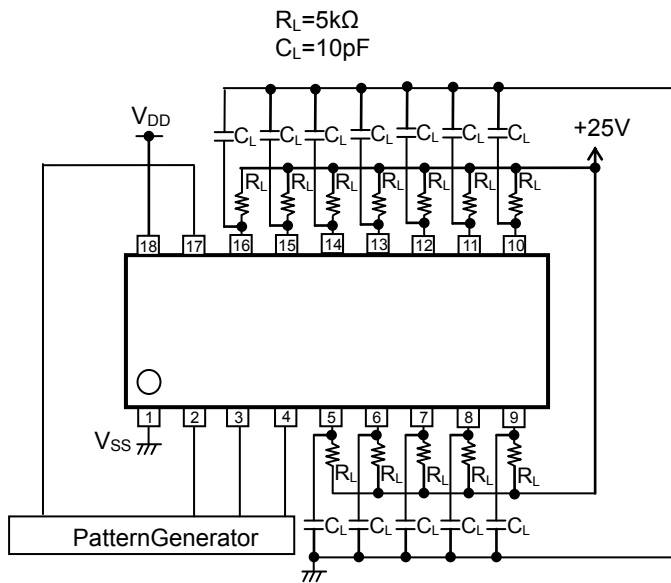
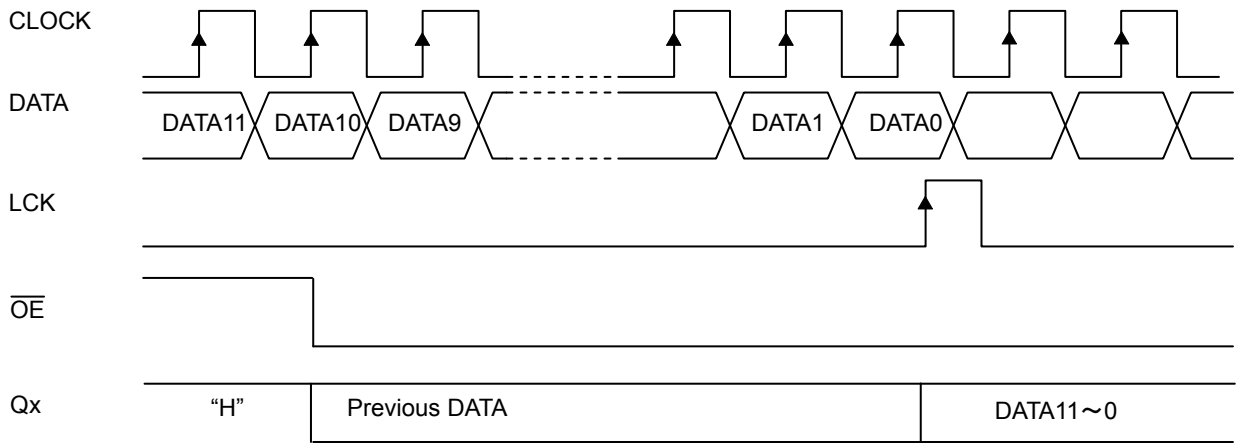


Figure 5. Test Circuit of Timing Characteristics

Timing Chart



(Note3) Diagram shows a status where a pull-up resistor is connected to output.

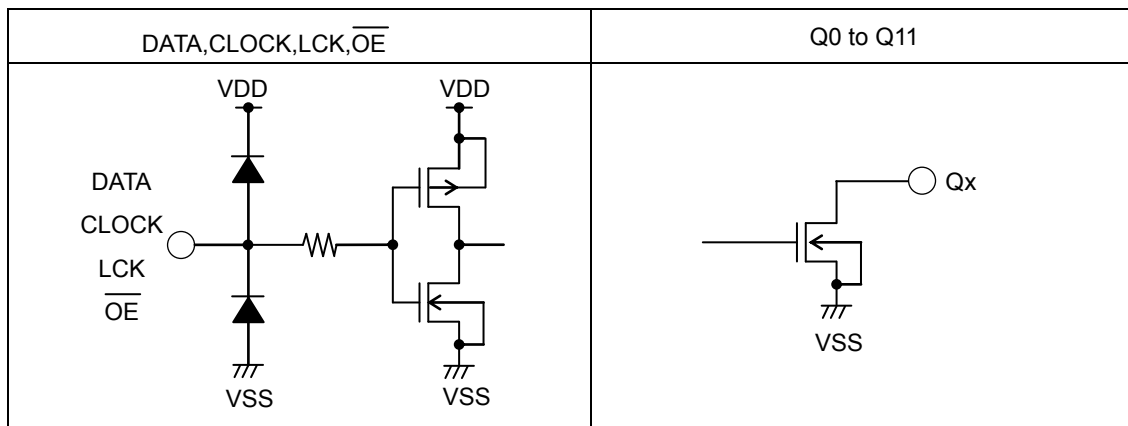
Figure 6 . Timing Chart

1. After the power is turned on and the voltage is stabilized, LCK should be activated, after clocking 12 data bits into the DATA terminal.
2. Qx parallel output data of the shift register is set after the 12<sup>th</sup> clock by the LCK.
3. Since the LCK is a label latch, data is retained in the "L" section and renewed in the "H" section of the LCK.
4. Data retained in the internal latch circuit is output when the OE is in the "L" section.

[Truth Table]

Input				Function
CLOCK	DATA	LCK	OE	
x	x	x	H	Output (Q0 to Q11) Disable
x	x	x	L	Output (Q0 to Q11) Enable
┌	L	x	x	Store "L" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
┌	H	x	x	Store "H" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
┐	x	x	x	The data of shift register has no change.
x	x	┌	x	The data of shift register is transferred to the storage register.
x	x	┐	x	The data of storage register has no change.

I/O Equivalence Circuits



**Power Dissipation**

Power dissipation(total loss) indicates the power that can be consumed by IC at  $T_A=25^{\circ}\text{C}$ (normal temperature). IC is heated when it consumed power, and the temperature of IC chip becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip(maximum junction temperature) and thermal resistance of package(heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage temperature range. Heat generated by consumed power of IC radiates from the mold resin or lead frame of the package. The parameter which indicates this heat dissipation capability(hardness of heat release)is called thermal resistance, represented by the symbol  $\theta_{JA}$  ( $^{\circ}\text{C}/\text{W}$ ).The temperature of IC inside the package can be estimated by this thermal resistance. Figure 7 shows the model of thermal resistance of the package. Thermal resistance  $\theta_{JA}$ , ambient temperature  $T_A$ , maximum junction temperature  $T_{Jmax}$ , and power dissipation  $P_D$  can be calculated by the equation below:

$$\theta_{JA} = (T_{Jmax} - T_A) / P_D \quad (^{\circ}\text{C}/\text{W})$$

Derating curve in Figure 8 indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance  $\theta_{JA}$ . Thermal resistance  $\theta_{JA}$  depends on chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition.

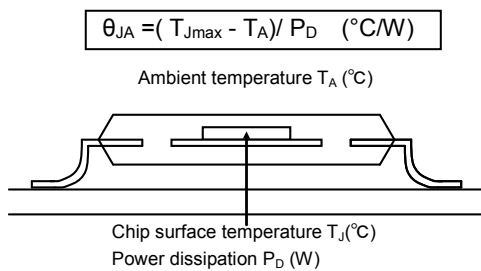


Figure 7. Thermal resistance

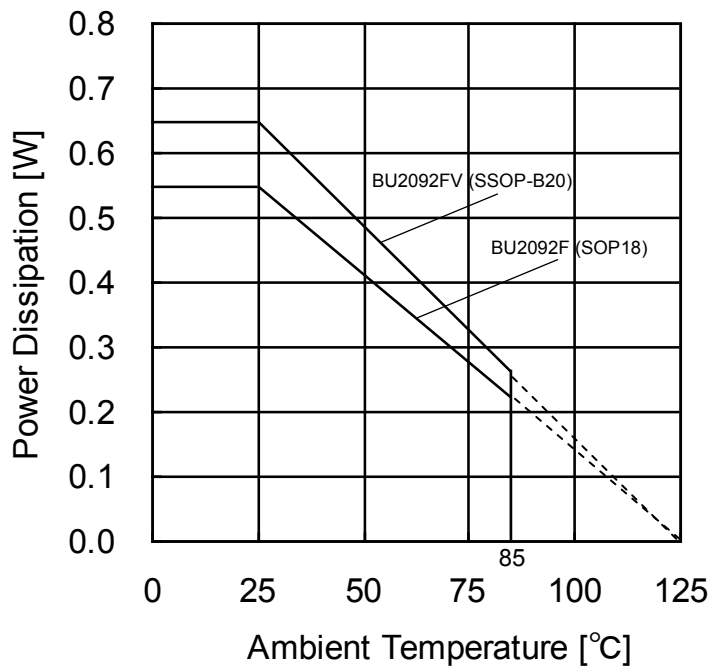


Figure 8. Derating Curve



## Operational Notes

### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

### 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

### 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

### 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

### 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

### 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

### 10. Inter-pin Short and Mounting Errors

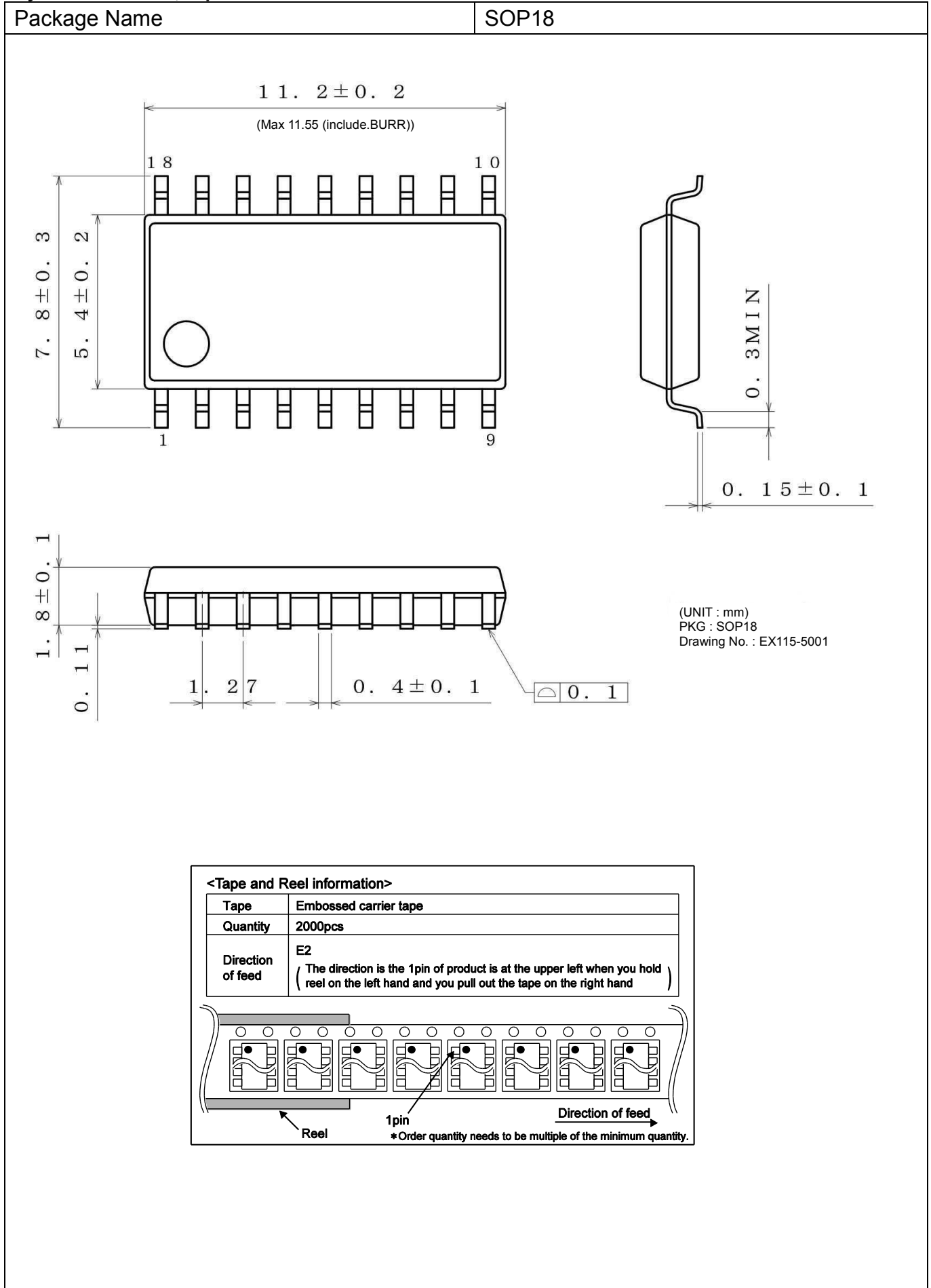
Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

### 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

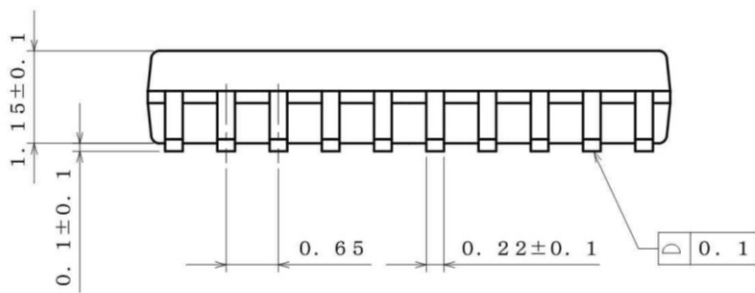
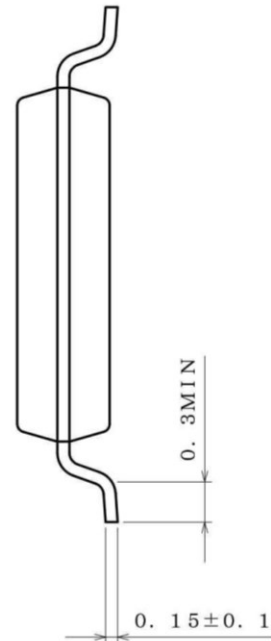
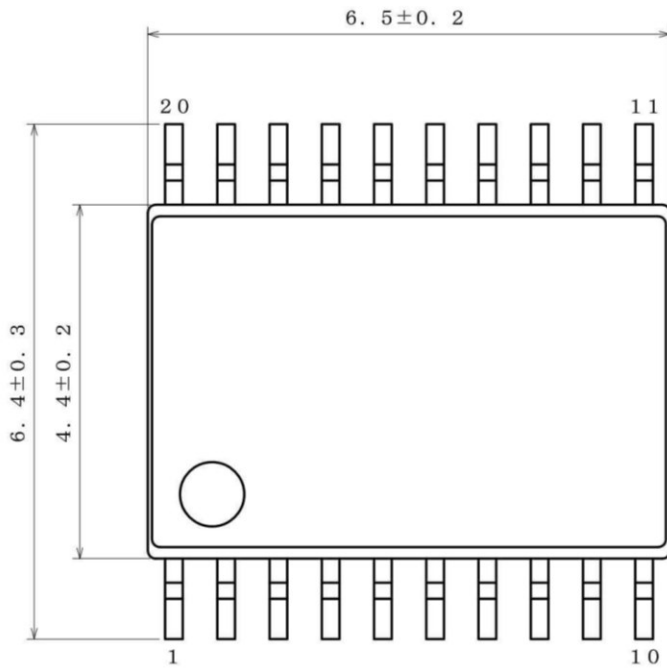


Physical Dimension, Tape and Reel Information



Physical Dimension, Tape and Reel Information– continued

Package Name	SSOP-B20
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(UNIT : mm)  
 PKG : SSOP-B20  
 Drawing No. ; EX154-5001

**<Tape and Reel information>**

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 ( The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand )

Reel      1pin      Direction of feed

\*Order quantity needs to be multiple of the minimum quantity.

## Revision History

Date	Revision	Changes
22.Nov.2013	001	New Release
18.Sep.2015	002	Page.1 Key Specifications Operating temperature range: -40°C to +85°C -> -25°C to +75°C

# Notice

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
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  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

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**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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